



Characterization of new stripixel detectors

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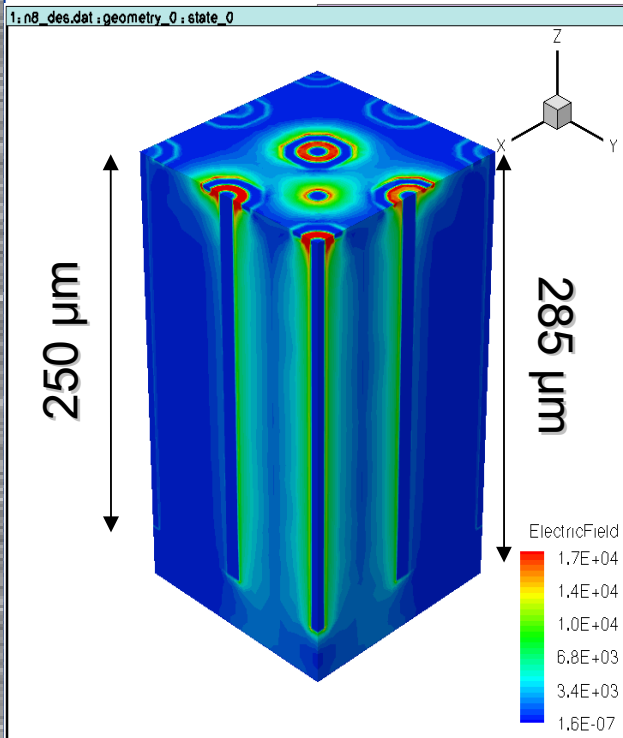
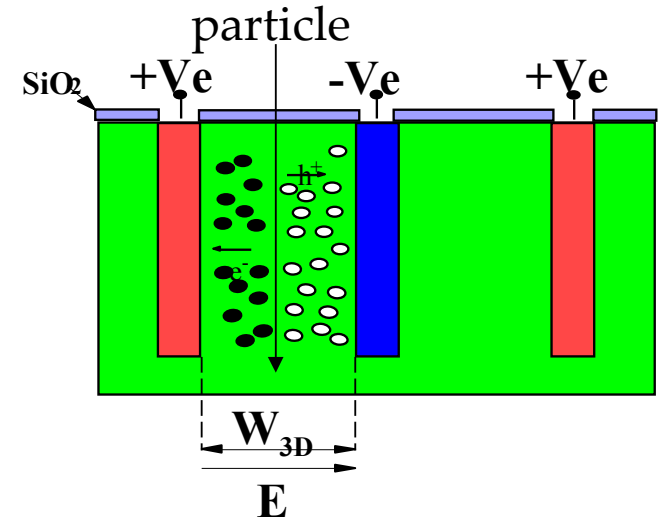
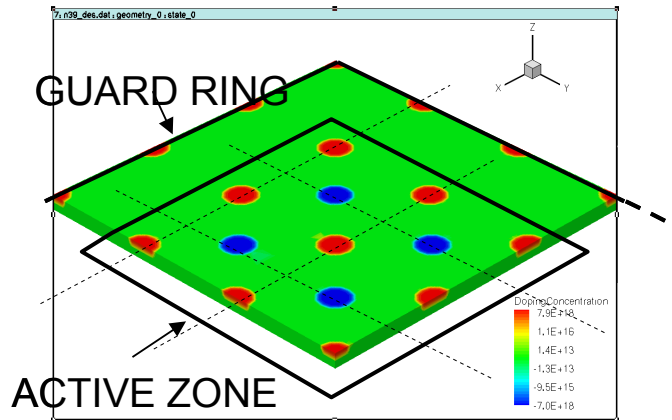
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Outline

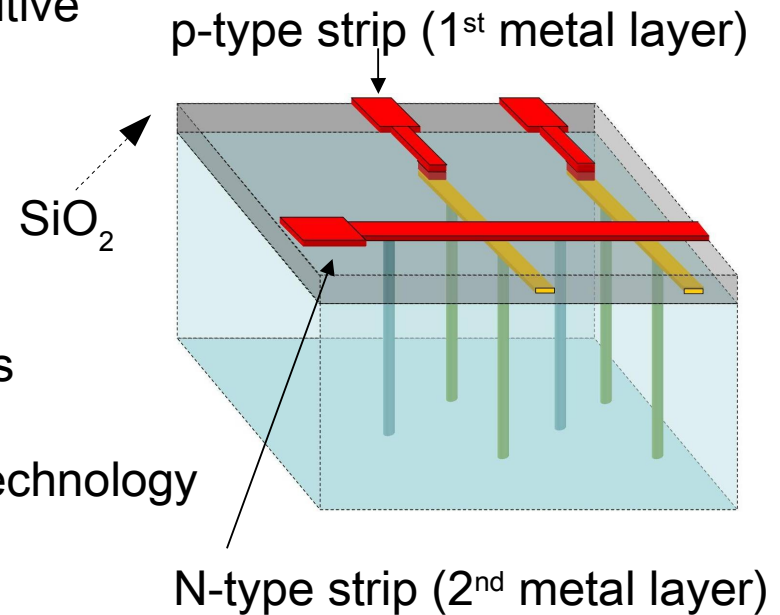
- New detectors design
- Optimization of the design:
simulation results
- Real prototypes
- Experimental results
- Conclusions

New design



2D position sensitive
3D technology

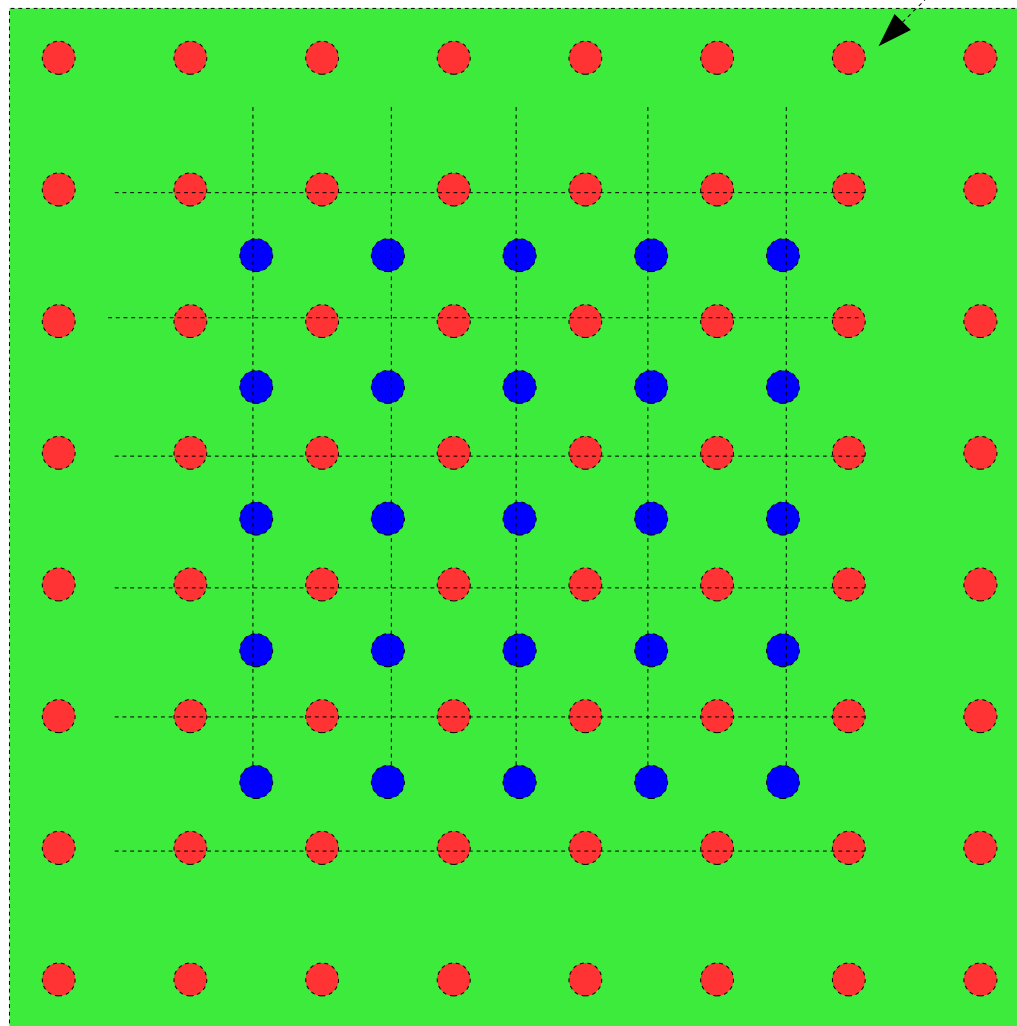
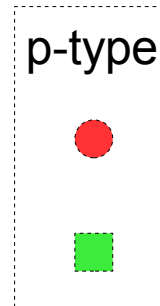
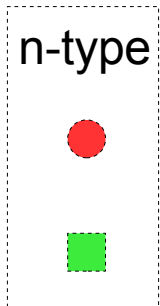
- Single sided
- Double columns
- P-stop rings
- Double metal technology



Design optimization

?

Guard ring



Simulation results:

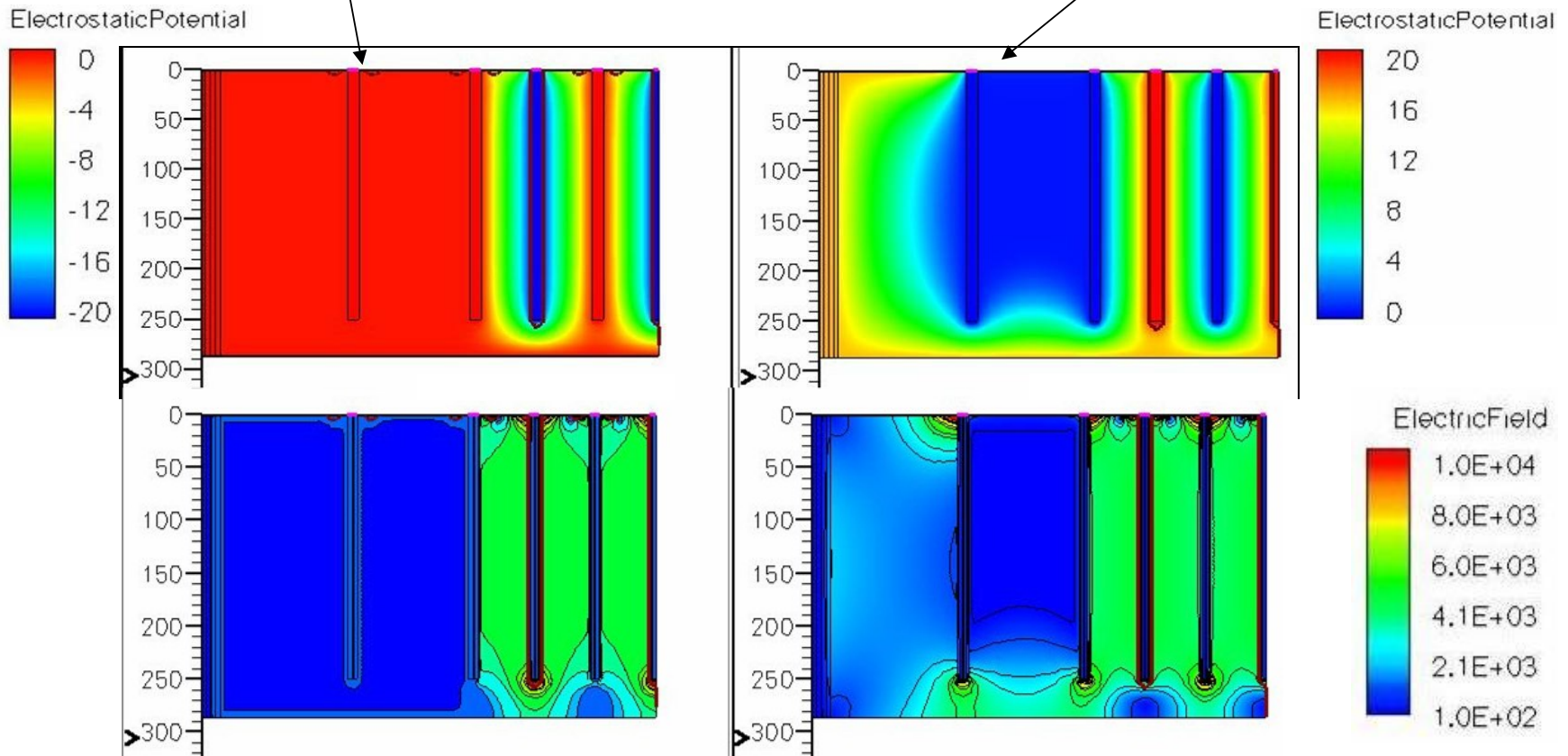
T-CAD Sentaurus simulations

Cut defects model: e⁻, h neutral traps.

Active area better defined with n-type bulk and guard ring!

n-type bulk, n-type guard ring

VS p-type bulk, p-type guard ring

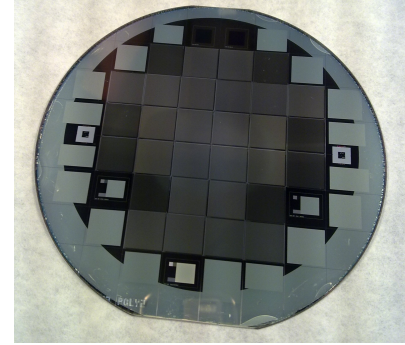


Thanks to Marie Ruat for collaborating in the simulation study

Real prototypes

Produced at the IMB-CNM, CSIC clean room facilities in Barcelona (ES)

6 wafers 285 μm thick, 1 wafer SOI 20 μm thick.

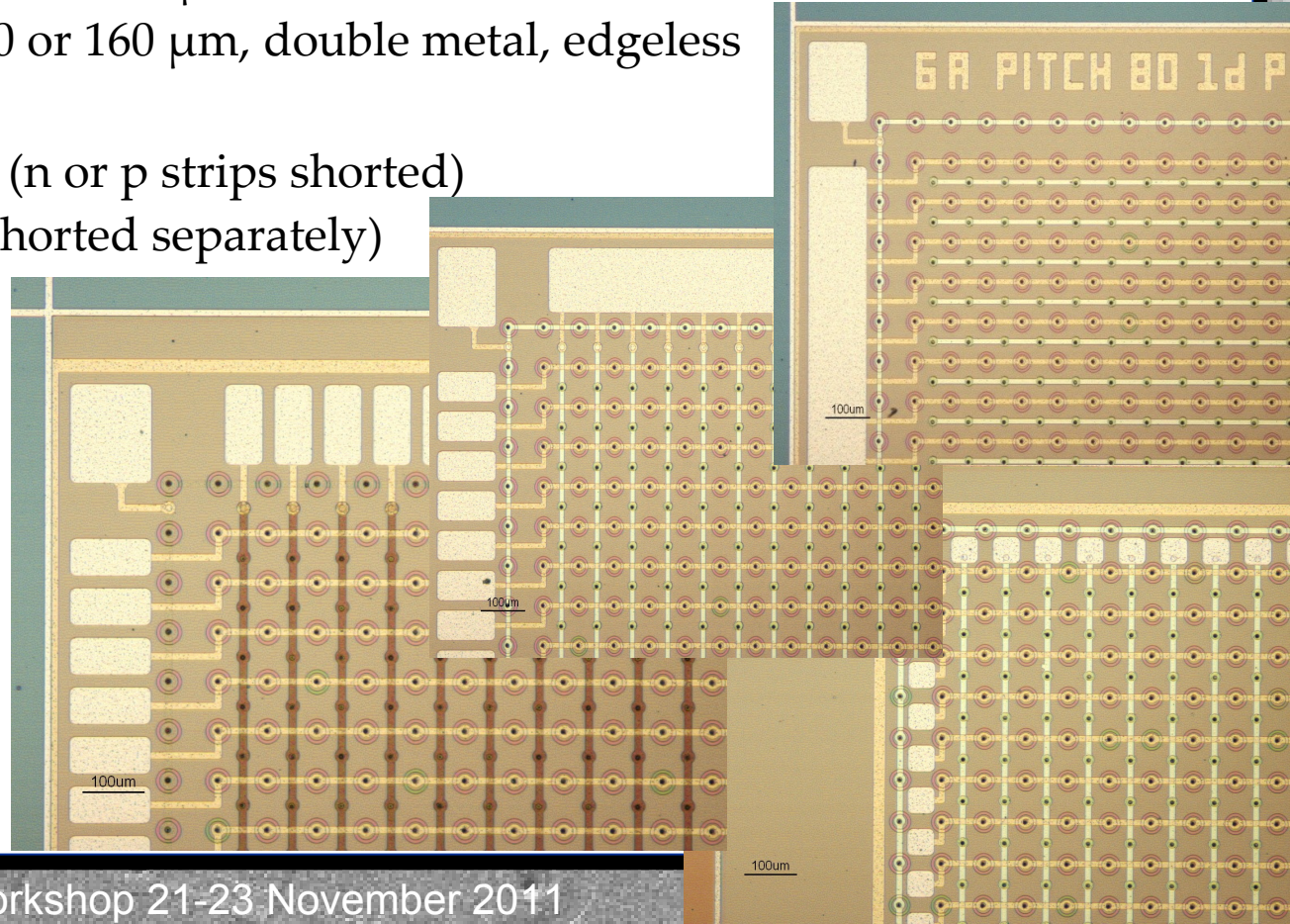
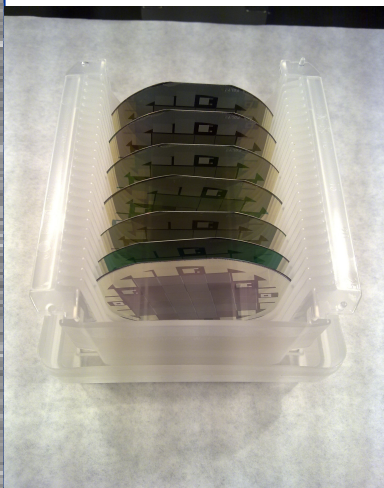


Detector structures:

- pitch 80 or 160 μm , double metal
- pitch 80 or 160 μm , double metal, edgeless

Test structures:

- 1D microstrip detectors (n or p strips shorted)
- Diodes (n and p strips shorted separately)



Electrical characterization

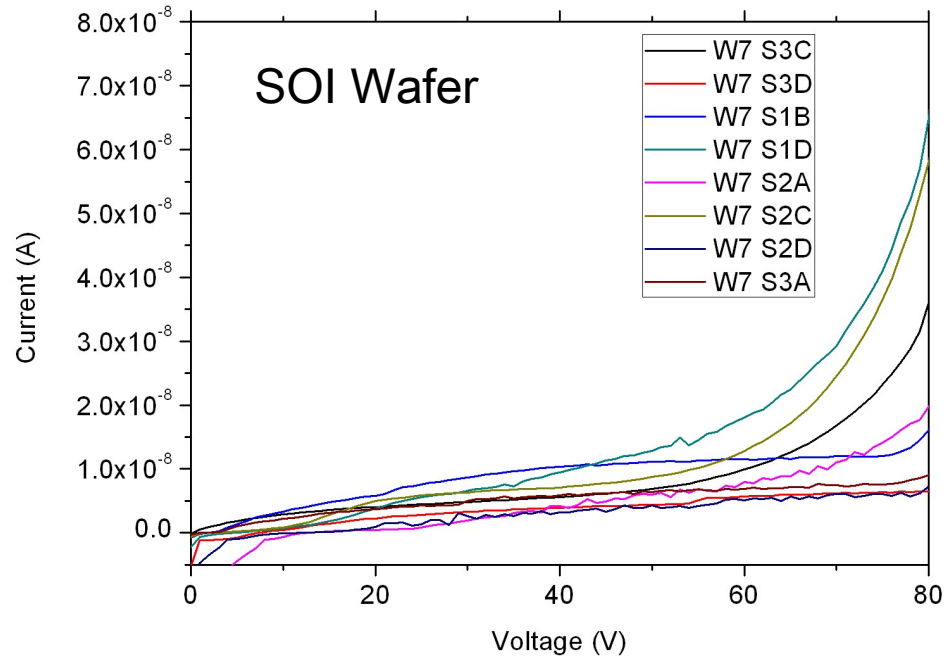
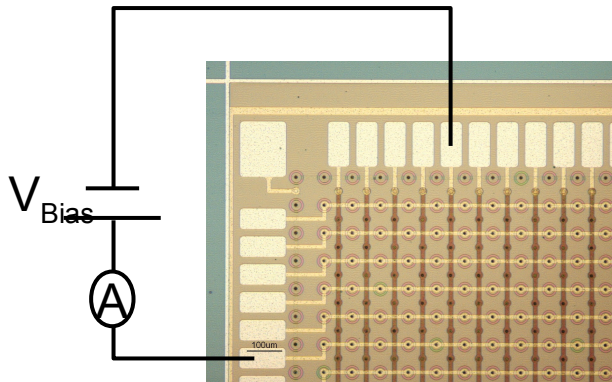
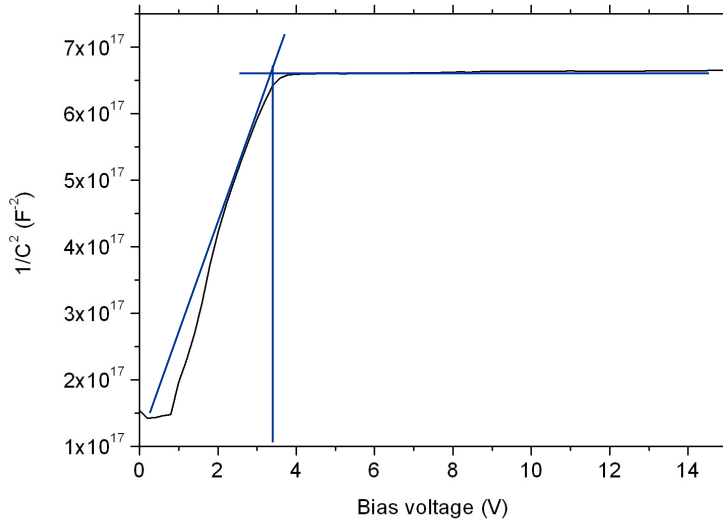
$T=20^{\circ}\text{C}$, $f=10\text{kHz}$

Depletion voltage
 $< 4\text{V} <$ breakdown
voltage

$C_{\text{bulk}} \sim 8\text{ pF}$

$I_{\text{leakage}} \sim \text{few nA (columns } 20\text{ }\mu\text{m deep)}$
 $10^2\text{ nA (columns } 250\text{ }\mu\text{m deep)}$

Only 1 p-type strip and 1 n-type strip have
been biased and read

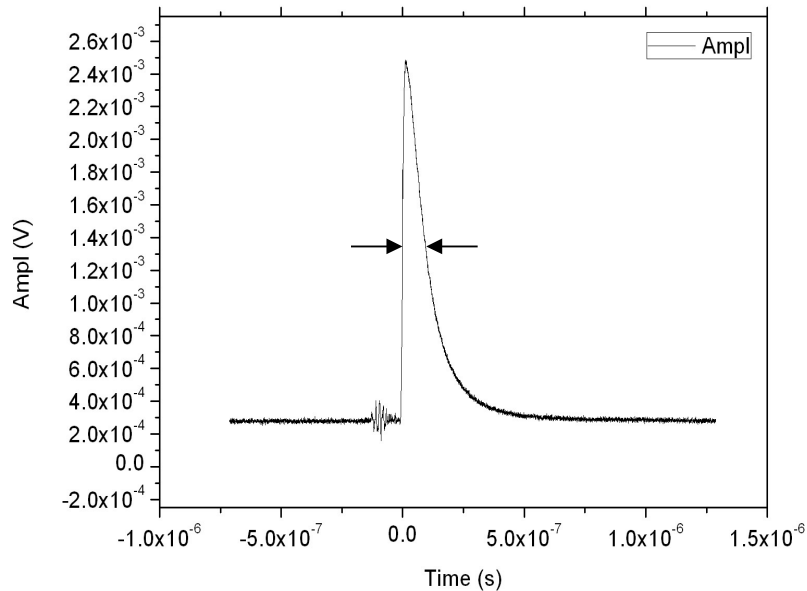


TCT measurements: setup

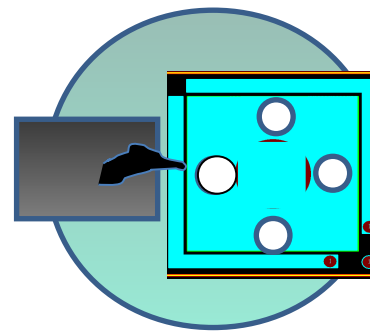
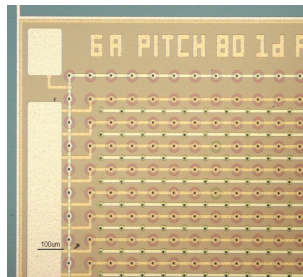
Carried out in the BNL (NY,USA) laboratories

Laser setup	Wavelength λ (nm)	Intensity (V)	Width (ns)	Period (μ s)	Penetration depth (μ m)
1 st	1060	10	10	20	whole bulk
2 nd	830	10	10	20	14
3 rd	660	10	10	20	4

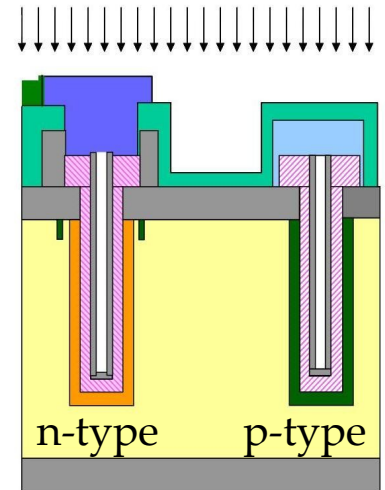
FWHM (Average Drift Time) = $f(1/\bar{E})$



Parallel strips



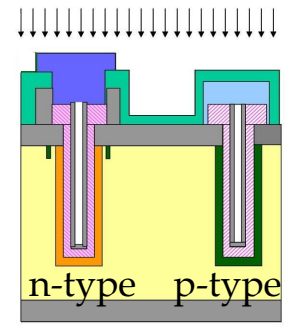
Laser beam (spot = 1mm)



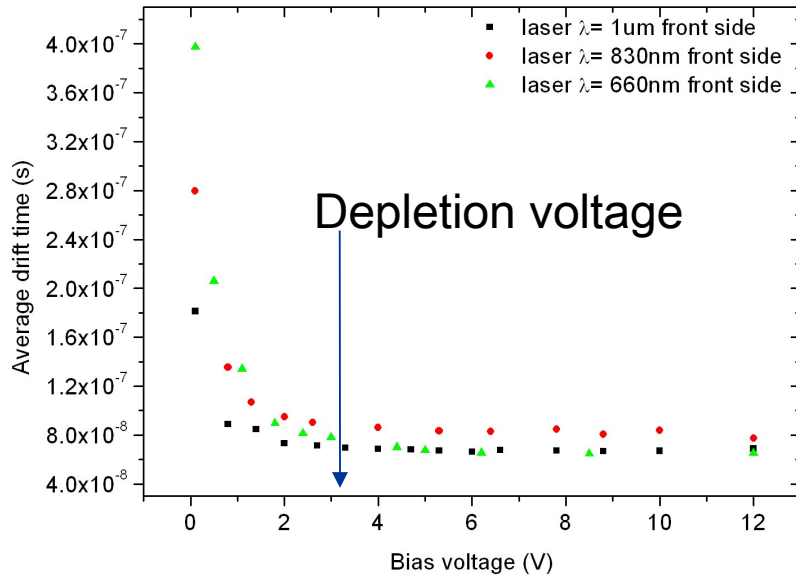
TCT measurements

Laser illuminating the front side

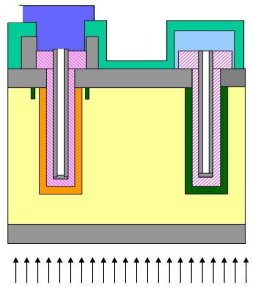
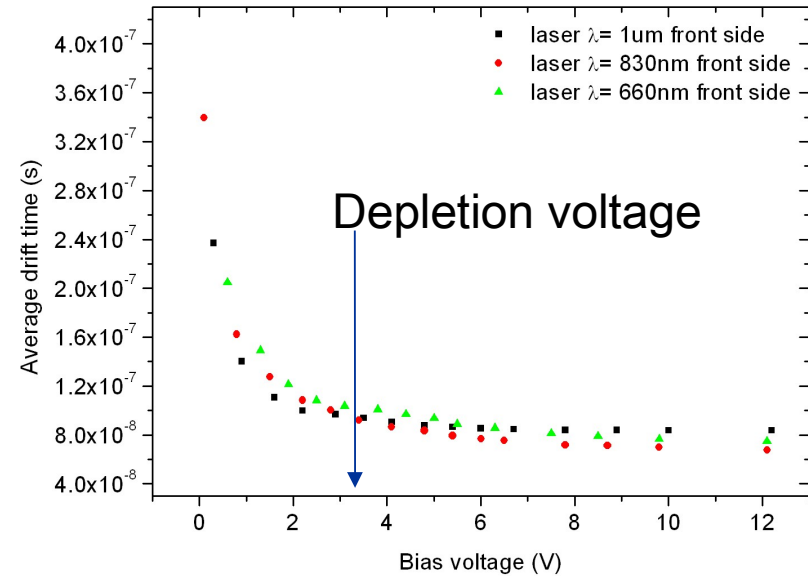
Signal read from both the electrodes



Signal read from the **n-type** electrodes



Signal read from the **p-type** electrodes

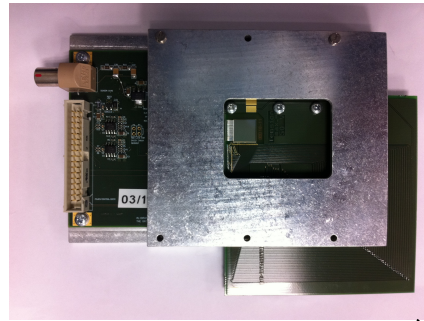


Illuminating the backside with both the lasers of shorter wavelengths (660 nm and 800 nm) any signal is read.

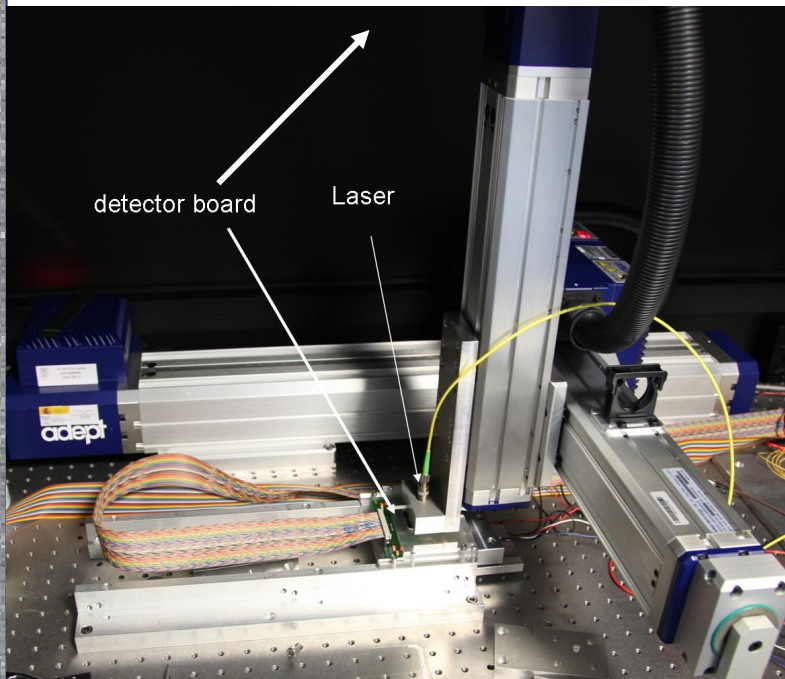
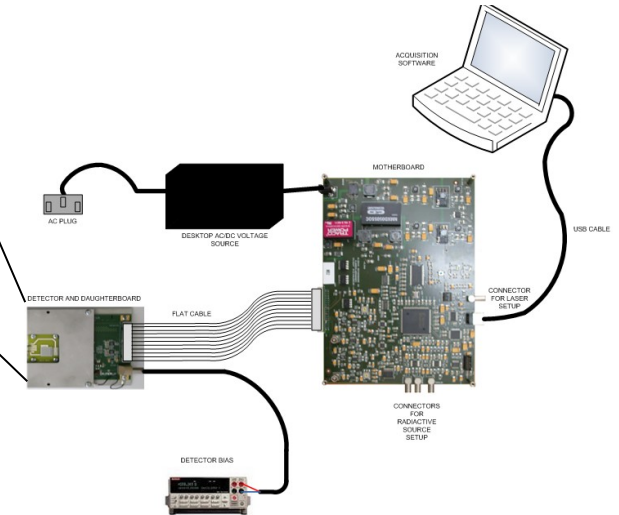
→ The last 14 μm never deplete

Laser characterization: setup

Carried out in the IFCA (Santander, Spain) clean room



Special detector board to connect n-type strips to one beetle chip and p-type strips to the other.



Pulsed DFB laser $\lambda=1060\text{nm}$

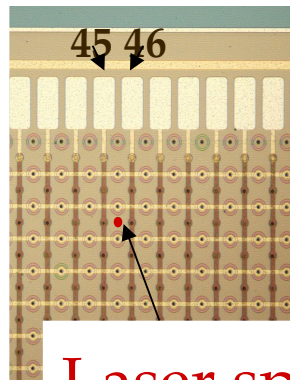
- Gaussian beam spot width $\approx 15 \mu\text{m}$

3D axis stage with displacement accuracy $\approx 10 \mu\text{m}$

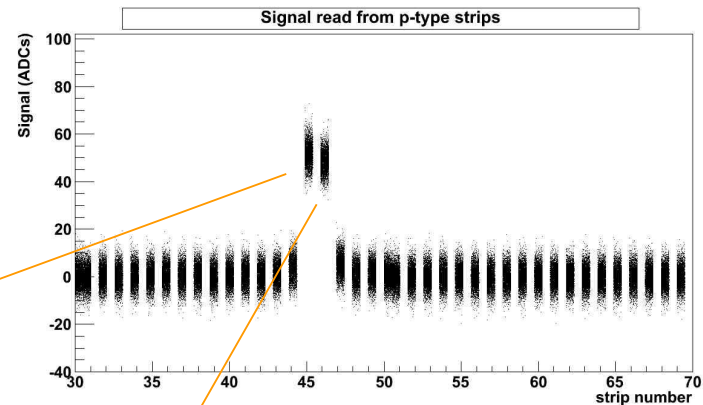
Thanks to the IFCA group for the measurements

Laser characterization

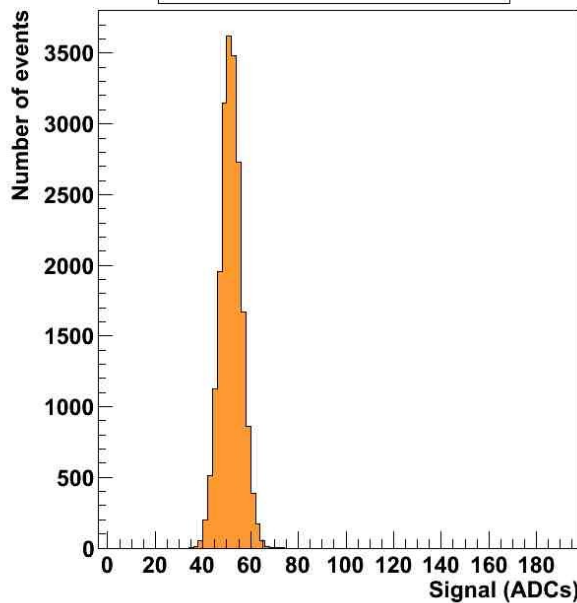
Laser spot centred in a pixel



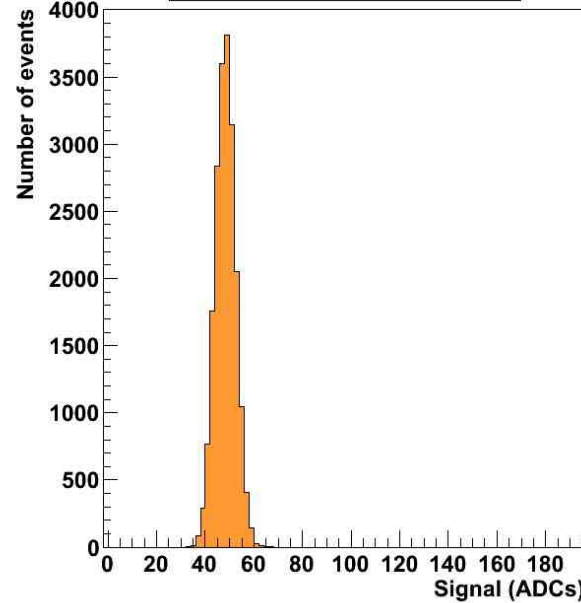
Laser spot



Signal read from strip 45



Signal read from strip 46



Average noise ~
2,5 ADCs

S/N~20

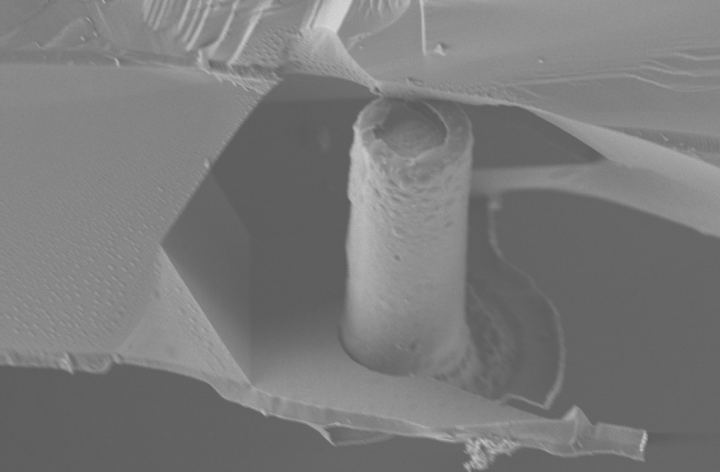
Laser signal > MIP!!!

No calibration!

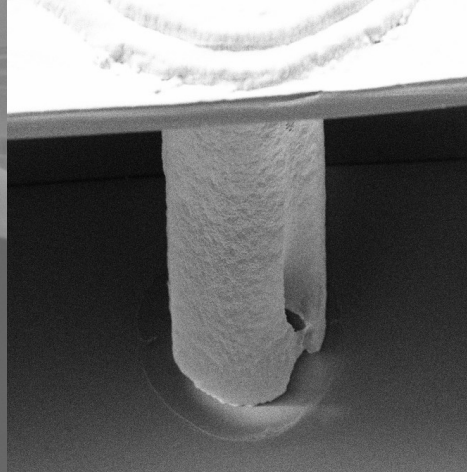
Conclusions

New 2D position-sensitive stripixel detectors have been manufactured using dual column electrodes and double metal layer technology in a true single-sided processing.

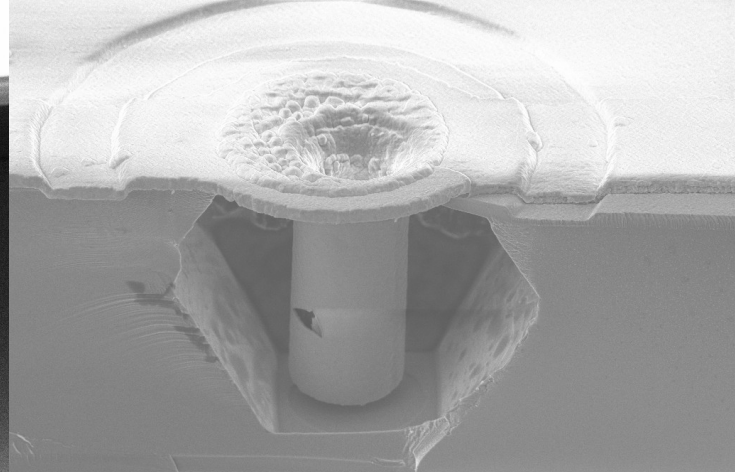
- 2D and 3D simulations have been used to optimize the design.
- Electrical characterization shows the lateral depletion voltage $< 4V <$ breakdown voltage.
- TCT measurements demonstrate both the n-type and p-type strips can be read.
- A preliminary laser measurement shows the good response of the devices.
- A full laser characterization and CCE measurements are in process using the ALIBAVA readout system.



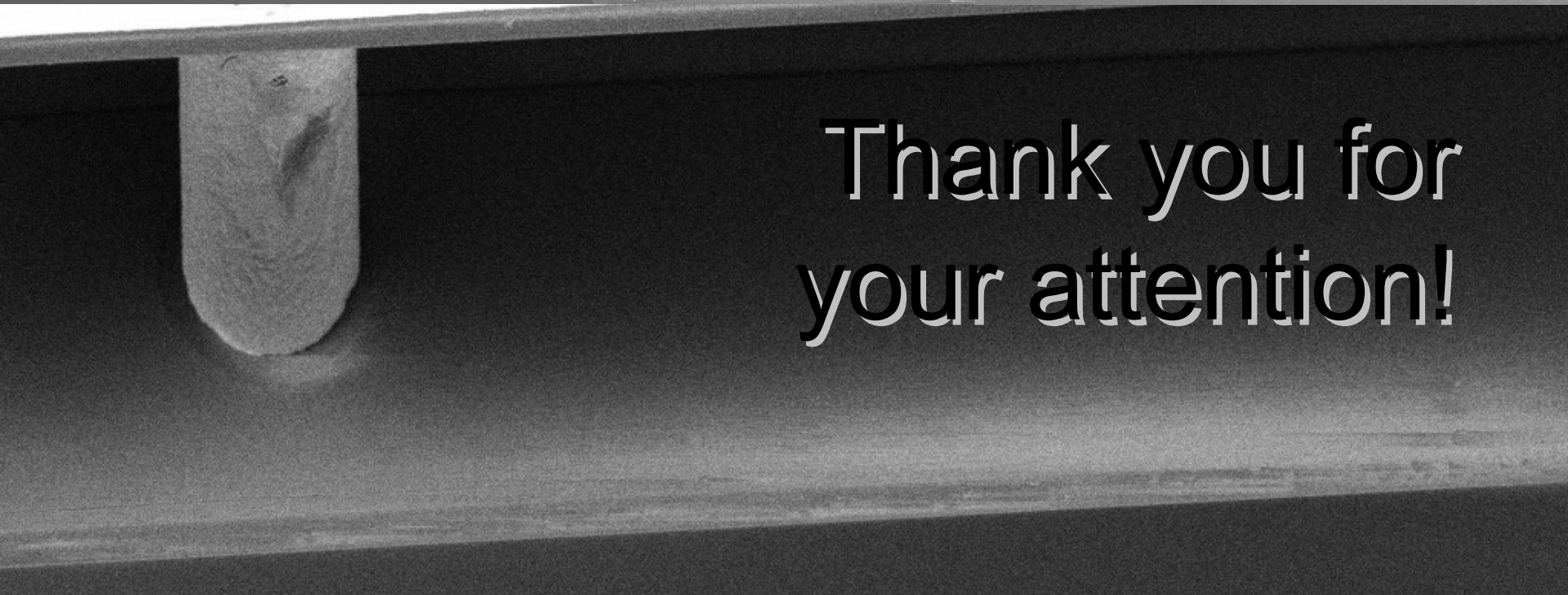
2 μ m
 Mag = 6.42 K X EHT = 3.00 kV Signal A = SE2 CNM-IMB
 WD = 2.2 mm Aperture Size = 30.00 μ m Date :11 Feb 2011



Mag = 9.09 K X EHT = 3.00 kV Signal A = SE2
 WD = 10.4 mm Aperture Size = 30.00 μ m Date :18 Feb 2011



2 μ m
 Mag = 5.89 K X EHT = 3.00 kV Signal A = SE2 CNM-IMB
 WD = 8.3 mm Aperture Size = 30.00 μ m Date :11 Feb 2011



Thank you for
 your attention!

3 μ m
 Mag = 4.58 K X EHT = 3.00 kV Signal A = SE2 CNM-IMB
 WD = 10.4 mm Aperture Size = 30.00 μ m Date :18 Feb 2011